

2.5-V PHASE-LOCKED-LOOP CLOCK DRIVER

FEATURES

- Spread-Spectrum Clock Compatible
- Operating Frequency: 60 MHz to 220 MHz
- Low Jitter (Cycle-Cycle): ± 60 ps (± 40 ps at 200 MHz)
- Low Static Phase Offset: ± 50 ps
- Low Jitter (Period): ± 60 ps (± 30 ps at 200 MHz)
- 1-to-4 Differential Clock Distribution (SSTL2)
- Best in Class for $V_{OX} = V_{DD}/2 \pm 0.1$ V
- Operates From Dual 2.6-V or 2.5-V Supplies
- Available in a 28-Pin TSSOP Package
- Consumes < 100 - μ A Quiescent Current
- External Feedback Pins (FBIN, $\overline{\text{FBIN}}$) Are Used to Synchronize the Outputs to the Input Clocks
- Meets/Exceeds JEDEC Standard (JESD82-1) For DDRI-200/266/333 Specification
- Meets/Exceeds Proposed DDRI-400 Specification (JESD82-1A)
- Enters Low-Power Mode When No CLK Input Signal Is Applied or $\overline{\text{PWRDWN}}$ Is Low

APPLICATIONS

- DDR Memory Modules (DDR400/333/266/200)
- Zero-Delay Fan-Out Buffer

DESCRIPTION

The CDCVF855 is a high-performance, low-skew, low-jitter, zero-delay buffer that distributes a differential clock input pair (CLK, $\overline{\text{CLK}}$) to 4 differential pairs of clock outputs (Y[0:3], $\overline{\text{Y}}[0:3]$) and one differential pair of feedback clock outputs (FBOUT, $\overline{\text{FBOUT}}$). The clock outputs are controlled by the clock inputs (CLK, $\overline{\text{CLK}}$), the feedback clocks (FBIN, $\overline{\text{FBIN}}$), and the analog power input (AV_{DD}). When $\overline{\text{PWRDWN}}$ is high, the outputs switch in phase and frequency with CLK. When $\overline{\text{PWRDWN}}$ is low, all outputs are disabled to a high-impedance state (3-state) and the PLL is shut down (low-power mode). The device also enters this low-power mode when the input frequency falls below a suggested detection frequency that is below 20 MHz (typical 10 MHz). An input frequency-detection circuit detects the low-frequency condition and, after applying a >20 -MHz input signal, this detection circuit turns the PLL on and enables the outputs.

When AV_{DD} is strapped low, the PLL is turned off and bypassed for test purposes. The CDCVF855 is also able to track spread-spectrum clocking for reduced EMI.

Because the CDCVF855 is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up. The CDCVF855 is characterized for both commercial and industrial temperature ranges.

AVAILABLE OPTIONS

T_A	TSSOP (PW)
-40°C to 85°C	CDCVF855PW

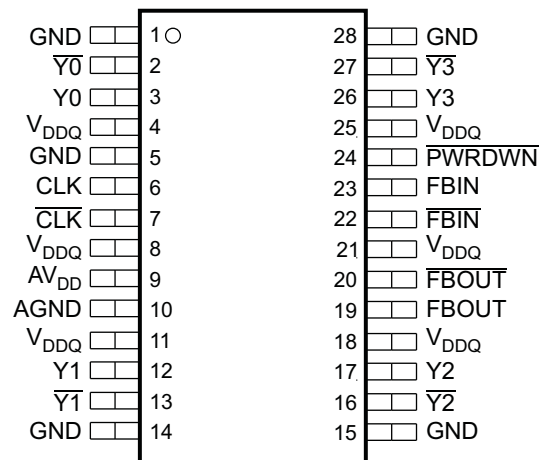


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**FUNCTION TABLE
(Select Functions)**

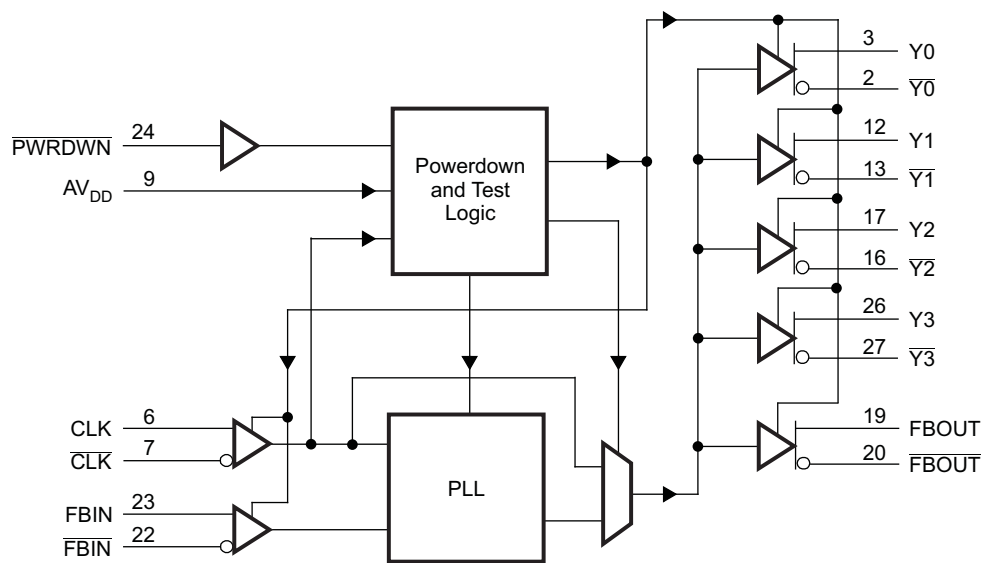
INPUTS				OUTPUTS				PLL
AVDD	PWRDWN	CLK	CLK	Y[0:3]	Y[0:3]	FBOUT	FBOUT	
GND	H	L	H	L	H	L	H	Bypassed/off
GND	H	H	L	H	L	H	L	Bypassed/off
X	L	L	H	Z	Z	Z	Z	Off
X	L	H	L	Z	Z	Z	Z	Off
2.5 V (nom)	H	L	H	L	H	L	H	On
2.5 V (nom)	H	H	L	H	L	H	L	On
2.5 V (nom)	X	<20 MHz	<20 MHz	Z	Z	Z	Z	Off

**PW PACKAGE
(TOP VIEW)**



P0043-02

FUNCTIONAL BLOCK DIAGRAM



B0196-02

Table 2. TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
AGND	10	–	Ground for 2.5-V analog supply
AV _{DD}	9	–	2.5-V analog supply
CLK, $\overline{\text{CLK}}$	6, 7	I	Differential clock input
FBIN, FBIN	22, 23	I	Feedback differential clock input
FBOU, $\overline{\text{FBOU}}$	19, 20	O	Feedback differential clock output
GND	1, 5, 14, 15, 28	–	Ground
PWRDWN	24	I	Output enable for Y and $\overline{\text{Y}}$
V _{DDQ}	4, 8, 11, 18, 21, 25	–	2.5-V supply
$\overline{\text{Y0}}$, Y0	2, 3	O	Buffered output copies of input clock, CLK, $\overline{\text{CLK}}$
Y1, $\overline{\text{Y1}}$	12, 13	O	Buffered output copies of input clock, CLK, $\overline{\text{CLK}}$
$\overline{\text{Y2}}$, Y2	16, 17	O	Buffered output copies of input clock, CLK, $\overline{\text{CLK}}$
Y3, $\overline{\text{Y3}}$	26, 27	O	Buffered output copies of input clock, CLK, $\overline{\text{CLK}}$

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

V _{DDQ} , AV _{DD}	Supply voltage range		0.5 V to 3.6 V
V _I	Input voltage range ⁽²⁾⁽³⁾		–0.5 V to V _{DDQ} + 0.5 V
V _O	Output voltage range ⁽²⁾⁽³⁾		–0.5 V to V _{DDQ} + 0.5 V
I _{IK}	Input clamp current	V _I < 0 or V _I > V _{DDQ}	±50 mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{DDQ}	±50 mA
I _O	Continuous output current	V _O = 0 to V _{DDQ}	±50 mA
I _{DDS}	Continuous current to GND or V _{DDQ}		±100 mA
T _{stg}	Storage temperature range		–65°C to 150°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

(3) This value is limited to 3.6 V maximum.

THERMAL CHARACTERISTICS

R _{θJA} for TSSOP Package ⁽¹⁾	
Airflow	High K
0 ft/min (0 m/min)	94.4°C/W
150 ft/min (45.72 m/min)	82.8°C/W

(1) The package thermal impedance is calculated in accordance with JESD 51.

RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
Supply voltage	V _{DDQ}	PC1600 – PC3200	2.3		2.7	V
	AV _{DD}		V _{DDQ} – 0.12		2.7	
V _{IL} Low-level input voltage	CLK, $\overline{\text{CLK}}$, FBIN, $\overline{\text{FBIN}}$				V _{DDQ} /2 – 0.18	V
	PWRDWN		–0.3		0.7	
V _{IH} High-level input voltage	CLK, $\overline{\text{CLK}}$, FBIN, $\overline{\text{FBIN}}$		V _{DDQ} /2 + 0.18			V
	PWRDWN		1.7		V _{DDQ} + 0.3	
DC input signal voltage ⁽¹⁾			–0.3		V _{DDQ} + 0.3	V
V _{ID} Differential input signal voltage ⁽²⁾	DC	CLK, FBIN	V _{DDQ} = 2.3 V – 2.7 V	0.36	V _{DDQ} + 0.6	V
			V _{DDQ} = 2.425 V – 2.7 V	0.25	V _{DDQ} + 0.6	
	AC	CLK, FBIN	V _{DDQ} = 2.3 V – 2.7 V	0.7	V _{DDQ} + 0.6	
			V _{DDQ} = 2.425 V – 2.7 V	0.49	V _{DDQ} + 0.6	
V _{IX} Input differential pair cross voltage ⁽³⁾⁽⁴⁾			V _{DDQ} /2 – 0.2		V _{DDQ} /2 + 0.2	V
I _{OH} High-level output current					–12	mA
I _{OL} Low-level output current					12	mA
SR Input slew rate			1		4	V/ns
T _A Operating free-air temperature			–40		85	°C

- (1) The unused inputs must be held high or low to prevent them from floating.
- (2) The dc input signal voltage specifies the allowable dc execution of the differential input.
- (3) The differential input signal voltage specifies the differential voltage |VTR – VCP| required for switching, where VTR is the true input level and VCP is the complementary input level.
- (4) The differential cross-point voltage is expected to track variations of V_{CC} and is the voltage at which the differential signals must cross.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK} Input voltage, all inputs	V _{DDQ} = 2.3 V, I _I = –18 mA			–1.2	V
V _{OH} High-level output voltage	V _{DDQ} = min to max, I _{OH} = –1 mA	V _{DDQ} – 0.1			V
	V _{DDQ} = 2.3 V, I _{OH} = –12 mA	1.7			
V _{OL} Low-level output voltage	V _{DDQ} = min to max, I _{OL} = 1 mA			0.1	V
	V _{DDQ} = 2.3 V, I _{OL} = 12 mA			0.6	
V _{OD} Output voltage swing ⁽²⁾		1.1		V _{DDQ} – 0.4	V
V _{OX} Output differential cross-voltage ⁽³⁾	Differential outputs are terminated with 120 Ω, C _L = 14 pF (See Figure 3)	V _{DDQ} /2 – 0.1	V _{DDQ} /2	V _{DDQ} /2 + 0.1	V
I _I Input current	V _{DDQ} = 2.7 V, V _I = 0 V to 2.7 V			±10	μA
I _{OZ} High-impedance-state output current	V _{DDQ} = 2.7 V, V _O = V _{DDQ} or GND			±10	μA
I _{DDPD} Power-down current on V _{DDQ} + AV _{DD}	CLK and $\overline{\text{CLK}}$ = 0 MHz; PWRDWN = Low; Σ of I _{DD} and AI _{DD}		20	100	μA
AI _{DD} Supply current on AV _{DD}	f _O = 170 MHz		6	8	mA
	f _O = 200 MHz		8	10	
C _I Input capacitance	V _{DDQ} = 2.5 V, V _I = V _{DDQ} or GND	2	2.5	3.5	pF

- (1) All typical values are at a nominal V_{DDQ}.
- (2) The differential output signal voltage specifies the differential voltage |VTR – VCP|, where VTR is the true output level and VCP is the complementary output level.
- (3) The differential cross-point voltage tracks variations of V_{DDQ} and is the voltage at which the differential signals must cross.

ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
I _{DD}	Dynamic current on V _{DDQ}	Without load	f _O = 170 MHz		65	80	mA
			f _O = 200 MHz		75	90	
		Differential outputs terminated with 120 Ω, C _L = 0 pF	f _O = 170 MHz		110	140	
			f _O = 200 MHz		120	150	
		Differential outputs terminated with 120 Ω, C _L = 14 pF	f _O = 170 MHz		130	160	
			f _O = 200 MHz		140	170	
ΔC	Part-to-part input capacitance variation	V _{DDQ} = 2.5 V, V _I = V _{DDQ} or GND				1	pF
C _{I(Δ)}	Input capacitance difference between CLK and CLK, FBIN and FBIN	V _{DDQ} = 2.5 V, V _I = V _{DDQ} or GND				0.25	pF

TIMING REQUIREMENTS

over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		MIN	MAX	UNIT
f _{CLK}	Operating clock frequency	60	220	MHz
	Application clock frequency	90	220	
Input clock duty cycle		40%	60%	
Stabilization time (PLL mode) ⁽¹⁾			10	μs
Stabilization time (bypass mode) ⁽²⁾			30	ns

- (1) The time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK and V_{DD} must be applied. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.
- (2) A recovery time is required when the device goes from power-down mode into bypass mode (AV_{DD} at GND).

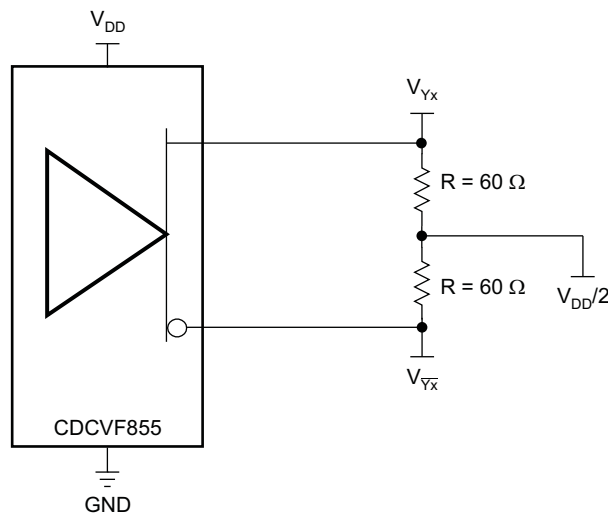
SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{PLH}^{(1)}$	Low- to high-level propagation delay time	Test mode/CLK to any output		3.5		ns
$t_{PHL}^{(1)}$	High- to low-level propagation delay time	Test mode/CLK to any output		3.5		ns
$t_{jit(per)}^{(2)}$	Jitter (period), see Figure 7	100/133/167 MHz (PC1600/2100/2700)	-65		65	ps
		200 MHz (PC3200)	-30		30	
$t_{jit(cc)}^{(2)}$	Jitter (cycle-to-cycle), see Figure 4	100/133/167 MHz (PC1600/2100/2700)	-60		60	ps
		200 MHz (PC3200)	-40		40	
$t_{jit(hper)}^{(2)}$	Half-period jitter, see Figure 8	100/133/167 MHz (PC1600/2100/2700)	-100		100	ps
		200 MHz (PC3200)	-75		75	
$t_{sLr(o)}$	Output clock slew rate, see Figure 9	Load: 120 Ω , 14 pF	1		2	V/ns
t_{ϕ}	Static phase offset, see Figure 5	100/133/167/200 MHz	-50		50	ps
$t_{sk(o)}$	Output skew, see Figure 6	Load: 120 Ω , 14 pF; 100/133/167/200 MHz			40	ps

- (1) Refers to the transition of the noninverting output.
- (2) This parameter is assured by design but cannot be 100% production tested.

PARAMETER MEASUREMENT INFORMATION



S0229-02

Figure 1. IBIS Model Output Load

PARAMETER MEASUREMENT INFORMATION (continued)

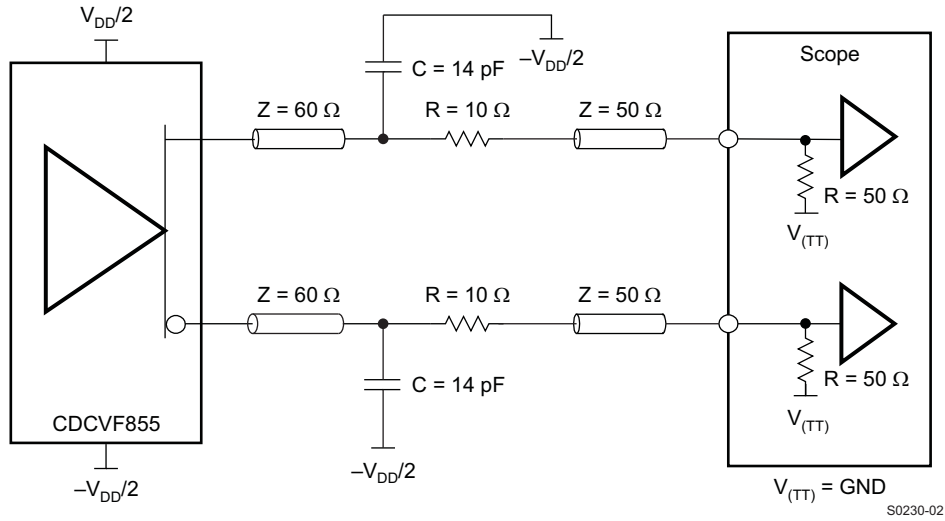


Figure 2. Output Load Test Circuit

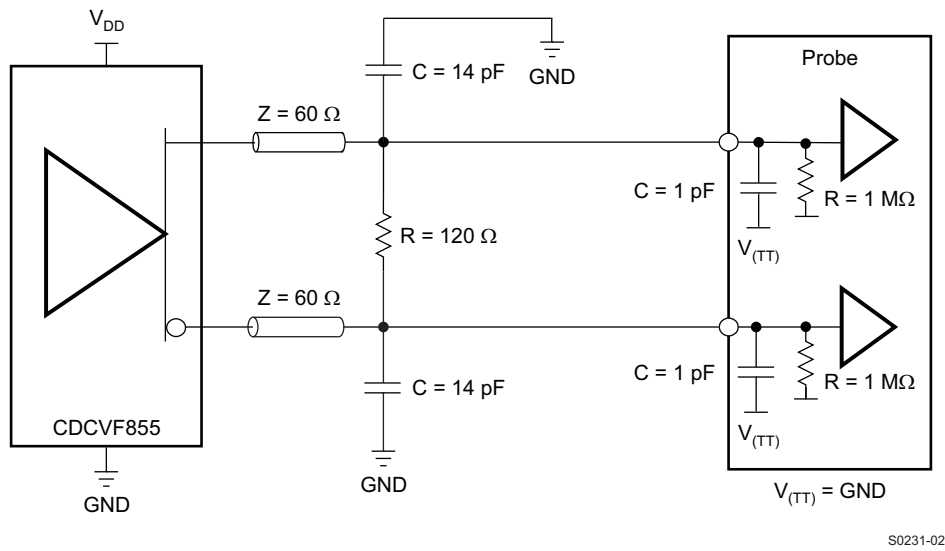


Figure 3. Output Load Test Circuit for Crossing Point

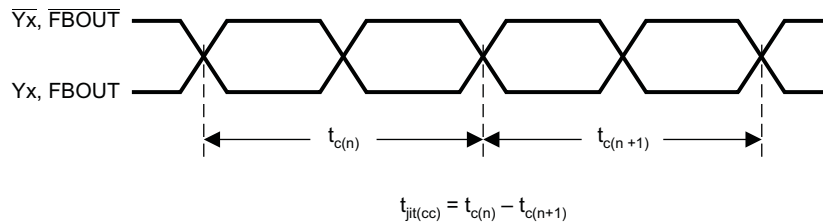
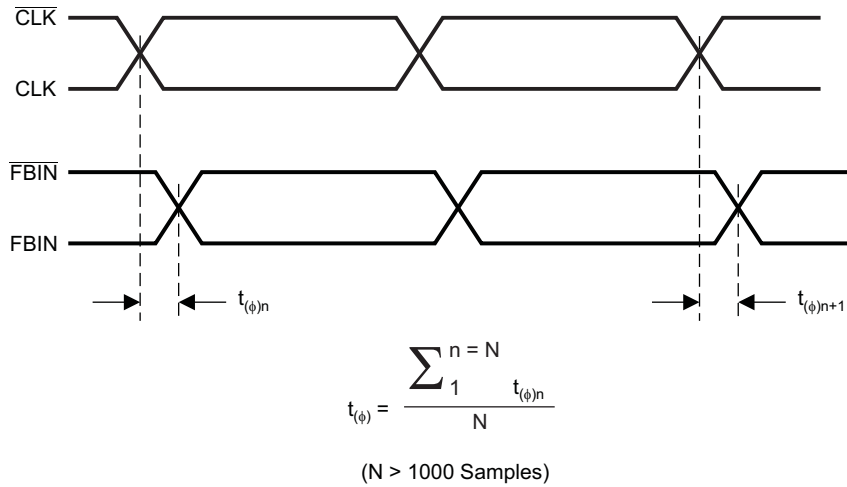


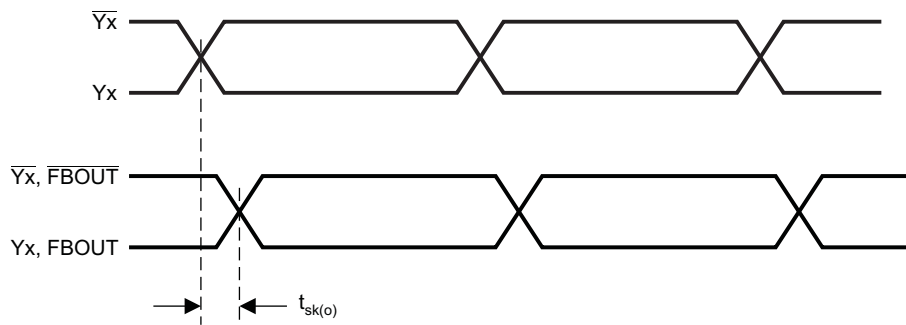
Figure 4. Cycle-to-Cycle Jitter

PARAMETER MEASUREMENT INFORMATION (continued)



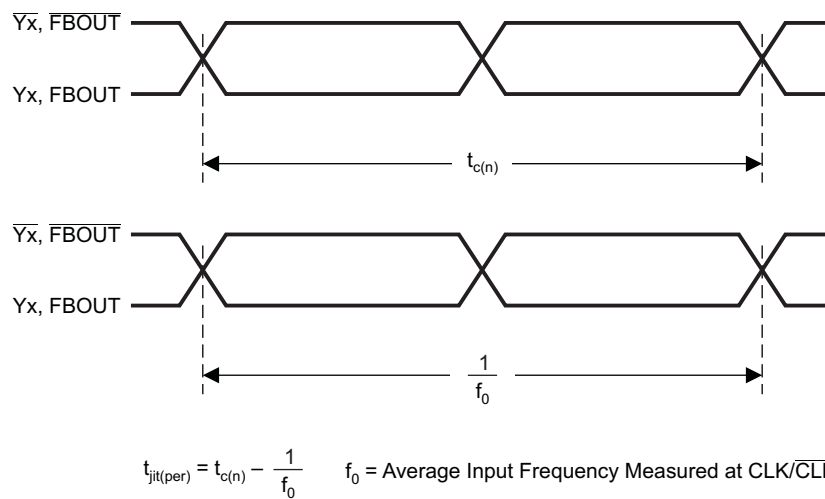
T0175-01

Figure 5. Phase Offset



T0176-01

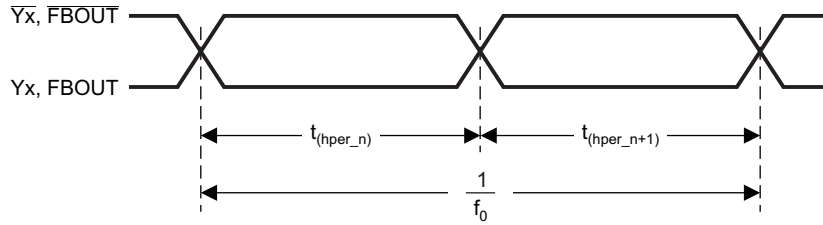
Figure 6. Output Skew



T0177-01

Figure 7. Period Jitter

PARAMETER MEASUREMENT INFORMATION (continued)

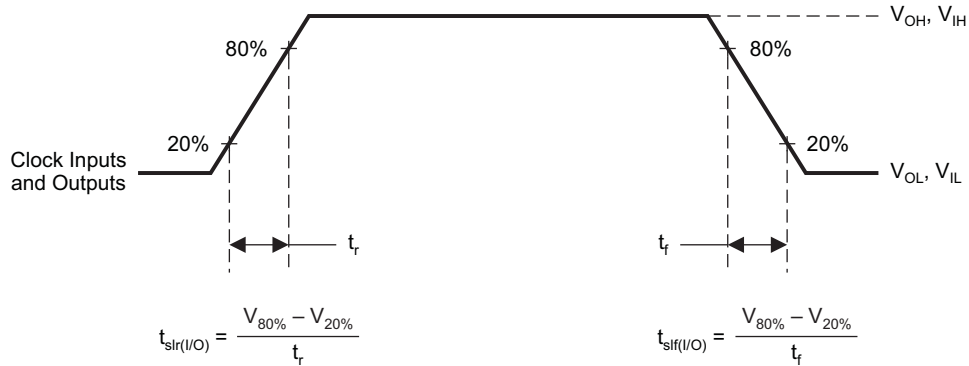


$$t_{jit(hper)} = t_{(hper_n)} - \frac{1}{2 \times f_0}$$

n = Any Half Cycle
f₀ = Average Input Frequency Measured at CLK/CLK

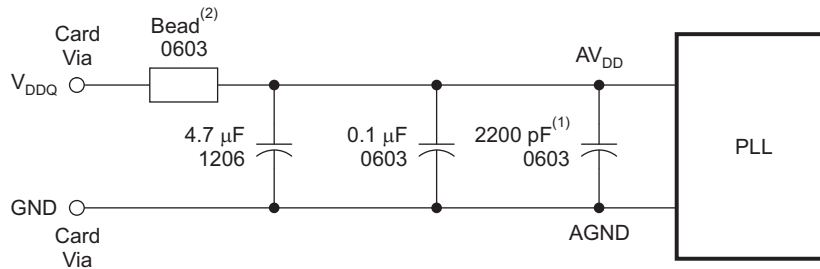
T0178-01

Figure 8. Half-Period Jitter



T0179-01

Figure 9. Input and Output Slew Rates



S0232-01

- (1) Place the 2200-pF capacitor close to the PLL.
- (2) Recommended bead: Fair-Rite P/N 2506036017Y0 or equivalent (0.8 Ω dc maximum, 600 Ω at 100 MHz).

NOTE: Use a wide trace for the PLL analog power and ground. Connect PLL and capacitors to AGND trace and connect trace to one GND via (farthest from the PLL).

Figure 10. Recommended AV_{DD} Filtering

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CDCVF855PW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		CDCVF855	Samples
CDCVF855PWG4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		CDCVF855	Samples
CDCVF855PWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		CDCVF855	Samples
CDCVF855PWRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		CDCVF855	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCVF855PWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCVF855PWR	TSSOP	PW	28	2000	367.0	367.0	38.0

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



4040064-7/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate design.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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